**敬愛的TEEMA會員先進　鈞鑒：**

**敬請卓參ICFPE 2018邀請函，盼望各位會員朋友踴躍投稿及參與今年ICFPE盛會。**

**2019 ICFPE又將來台，並與IMPACT (14th International Microsystems, Packaging, Assembly and Circuits Technology)合作舉辦，力邀您今年共襄盛舉、為ICFPE 2019暖身。謝謝。**

**［Call for Paper (both Oral & Poster)］：**[6/30](http://www.icfpe.org.cn/call-for-paper/%EF%BC%8C%E3%80%80%E9%9C%80%E6%96%BC6/30)前於線上提交摘要。2018年6月30日至7月15日，大會將以mail通知投稿者審查結果。投稿者需於7/30以前報名註冊以享有早鳥報名優惠。<http://www.icfpe.org.cn/call-for-paper/>

**［Call for Participation (Coupon Code: czipei1!)］：**早鳥期間至7/30截止。輸入大會優惠代碼（czipei1！）可以享受額外5％的折扣<http://www.icfpe.org.cn/registration-guide/>

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| ICFPE 2018 |

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| **9th International Conference on Flexible and Printed Electronics**Changzhou, China25-28 September, 2018 |

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| Invitation |

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| Dear Sir,On behalf of the organizing committee, we cordially invite you to participate in the **9th International Conference on Flexible and Printed Electronics (ICFPE 2018)**. The conference will be held from **September 25th to 28th** in **Changzhou, China**. ICFPE is one of the world’s major conferences in the area of printed electronics and flexible electronics, hosted annually by **Korea, Japan, China, or Taiwan** with strong participation worldwide. ICFPE is one of the world’s major conferences in the area of printed electronics and flexible electronics, with attendees usually more than 800 every year. This year's ICFPE is co-existed with **Flexible Electronics 2018** with anticipated strong Industry and end user participation and the 1st **Demo Competition** with great support from **China Government** and famous investment institutions, including **Sequoia Capital, SAIF Partners, Goldman Sachs, Cowin Capital, Hony Capital, Co-Stone Capital, Real Power Capital and Guohe Capital, etc**.We are looking forward to hearing from you in the near future!  |

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| Organizers |

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| Co-Organizers |

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| Insert alt text hereInternational Conference on Flexible and Electronics 2018 |
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| [Learn more about ICFPE 2018](http://link.r2dmm.com/redirect.php?id=PDg3ODY0ZDhkZGNiYmY5YTMyYmRhN2UzZTBmNjEyZDg0QGxpbmsucjJkbW0uY29tPg%3D%3D&ref=aHR0cDovL2ljZnBlLm9yZy5jbg%3D%3D&e=1) |

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| **Who Will You Meet?** |

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| **Industry** | **Academic & Research** |
| 3GSolar Photovoltaics Ltd | Kent Displays, Inc. | Beijing Institute of Graphic Communication |
| 3M | Kroenert GmbH & Co. KG  | Beijing Institute of Technology |
| adphos Digital Printing GmbH | LEITAT  | Brno University of Technology |
| Adphos North America, Inc. | LG | Brunel University London |
| Advantech U.S., Inc. | Linear Technology | Cal Poly ~ Printed Electronics & Functional Imaging |
| Agfa-Gevaert | Liquid X Printed Metals, Inc. | Canadian Printable Electronics Industry Association (CPEIA) |
| Altana | Lohmann GmbH & Co. KG  | Central South University |
| American Semiconductor, Inc. | LunaLEC | Centre for Nanotechnology and Smart Materials (CeNTI) |
| AMPAC Fine Chemicals | Materion Corporation | Changzhou Institute of Printed Electronics Industry |
| Apple | MC10, Inc. | Clemson University |
| Applied Materials | Mentor | Dalian University of Technology |
| Ares Materials, Inc.  | Merck KGaA | Eindhoven University of Technology |
| Arjowiggins Creative Papers | Meyer Burger | Feng Chia University |
| Arkema  | Mitsubishi Chemical Corporation  | FlexTech Alliance |
| Asahi Kasei | MOCON, Inc. | Fraunhofer ENAS |
| Avery Dennison | Molex | Fraunhofer FEP |
| BASF | MPI Corporation | Fraunhofer IAP |
| BeBop Sensors | Mycronic AB | Fraunhofer IFAM |
| Bluestone Global Tech | Nagase | Fraunhofer Institute for Solar Energy Systems ISE |
| BOE | NanoSolar Inc. | Fraunhofer ISIT |
| Bosch Rexroth AG | Neotech AMT GmbH | Georg Simon Ohm University of Applied Sciences |
| Botest Systems GmbH | NeuDrive Ltd.  | Georgia Tech - Center for Organic Photonics and Electronics |
| Brewer Science | Nissan Chemical | Hanyang University |
| Brewer Science, Inc.  | NLAB Solar AB | Hebrew University of Jerusalem |
| Cambridge Display Technology Ltd | Notion Systems GmbH | Holst Centre |
| Cambrios Technologies | NovaCentrix | Hongik University |
| Canberra Industries Inc. | nTact | Hoseo University |
| Carestream | Optomec | IDTechEx |
| Ceradrop | OPVIUS | IMEC  |
| Coatema Coating Machinery GmbH | Organic Electronic Technologies P.C | Imperial College London |
| Coherent GmbH | Oxford Photovoltaics | Inha University |
| Continental Automotive GmbH | Pall Corporation | Innovation Association of Printed Electronics |
| Corning | Paper Battery Company | Institute of Chemistry Chinese Academy of Sciences |
| Coruna Printed Electronics GmbH | Phoseon Technology | ITRI |
| Coveme | Piezotech, an Arkema Group Company | Japan Society for Promotion of Machine Industry |
| CreaPhys GmbH | Polyera Corporation | JAPERA |
| CSEM SA | PolyIC GmbH & Co. KG | JDSU |
| CSOT | Poly-Ink | Johannes Kepler University |
| CVD Equipment Corporation | Polyonics Inc. | Kent State University |
| Cymbet | PolyPhotonix Ltd. | KITECH |
| Cynora | Printed Electronics Ltd. | Kongju National university  |
| DNP Corporation | Promethean Particles Ltd. | Konkuk University |
| Dow Chemical | Prototype & Production Systems, Inc. | KoPEA |
| Dow Corning | PST Sensors | Korea Advanced Institute of Science and Technology |
| DOWA | PV Nano Cell | Korea High Tech Textile Research Institute |
| DP Patterning AB | Pythagoras Solar | Korea Photonics Technology Institute |
| DuPont | Qualcomm | KRICT |
| DuraTech Industries, Inc. | Raynergy Tek Incorporation | Kyung Hee University |
| E Ink Corporation | R-Display & Lighting, LLC | Kyushu University |
| Eastman Chemical | Renesas Electronics | Lamar University |
| ELANTAS | Robert Bosch | Nanchang University |
| Enfucell Oy | Rockwell Collins | National Central University |
| Engineered Materials Systems, Inc. | Royole Corporation | National Cheng Kung University |
| EverDisplay Optronics | Sabic Innovative Plastics | National Chiao Tung University |
| Evonik Degussa | SAES Getters | National Institute of Advanced Industrial Science and Technology |
| EXAKT Advanced Technologies GmbH | Saint-Gobain | National Sun Yat Sen University |
| Exeger Sweden AB | SAIT | National Taiwan University |
| Felix Böttcher GmbH & Co. KG | Samsung | North Carolina State University - ASSIST Center |
| Felix Schoeller Group | Sartomer  | Northeastern University |
| Ferro | Schneider Electric | Northumbria University |
| FHR Anlagenbau GmbH | Schoeller Technocell GmbH & Co. KG | OE-A (Organic and Printed Electronics Association) |
| Fiamm S.p.A. | Semilab | Okayama University |
| First Solar, Inc. | Shanghai Mifang | PARC (Palo Alto Research Center), a Xerox company |
| Firstbeat Technologies Ltd | Sharp Laboratories  | PETS (Printed Electronics Total Solution Development) |
| Fischer Technology | Sigma-Aldrich | Pusan National University |
| Flex | Smartkem Ltd. | Seoul National University |
| FlexEnable Ltd | Sol Voltaics  | Shanghai Institute of Ceramics, Chinese Academy of Sciences |
| FRAMOS GmbH | Solvay | Shanghai Jiao Tong University |
| Fujifilm Dimatix Inc.  | STMICROELECTRONICS | Shanghai University |
| GE | Sumitomo Chemical | Shizuoka University |
| General Label | Sun Chemical  | Sichuan University |
| Genes' Ink | SunaTech Inc. | South China Normal University |
| Glas Trosch AG | T+Ink, Inc. | South China University of Technology |
| Global Solar Energy Inc | Tangio Printed Electronics | Southeast University |
| Grafoid Inc. | TCL | Sunchon National University |
| GrafTech International Holdings Inc. | Teijin Ltd. | Sungkyunkwan University |
| GRT GmbH & Co. KG  | Tekna | Suzhou Institute of Nanotech, Printable Electronics Research Center |
| GS Energy | Teknek Ltd.  | Tampere University of Technology |
| GSI Technologies  | Temicon GmbH  | Tampere University of Technology |
| GT+W GmbH | Texas Instruments | Technical University of Darmstadt |
| Guangdong Juhua Printing | Thermo Fisher Scientific | Technion - Israel Institute of Technology |
| Guardian Industries | THIEME GmbH & Co. KG | The Hebrew University of Jerusalem  |
| H.C. Starck GmbH | Thin Film Electronics ASA | The Printed Electronics and Intelligent Packaging Consortium |
| Haiku Tech, Inc. | Tianma | The University of Electro-Communications |
| Hamamatsu Corporation | Toppan  | Tianjin University of Science and Technology |
| Hankuk Glass Industries | Toray Advanced Materials  | Tongji University |
| Hans Frintrup GmbH | Toshiba | Tsinghua University |
| Haydale Limited  | Toyo Ink SC Holdings Co., Ltd. | Ulsan National Institute of Science and Technology |
| Heliatek GmbH | TOYOBO | University of California – Berkeley |
| Henkel Electronic Materials | TSE Troller | University of California Los Angeles (UCLA) |
| Heraeus | Universal Display Corp | University of Karlsruhe |
| Huawei  | Ushio | University of Massachusetts Amherst |
| ID Labels Pte Ltd | VARTA Microbattery | University of Michigan |
| Idemitsu | Visionox | University of Sheffield |
| Imprint Energy | VON ARDENNE GmbH | University of Singapore |
| Indium Corp. | Walsin Solar Technology Co., Ltd. | University of Stuttgart |
| Inkron | Xaar | University of the West of England |
| InkTec Co., Ltd. | XENON Corporation | University of Tokyo |
| Intel Corp | Xerox | Universty of Massachusetts Lowell |
| Intellivation LLC | XG Sciences | Utsunomiya University |
| Intematix | Xymox Technologies Inc.  | VTT Technical Research Centre |
| Interlink Electronics Inc | Ynvisible | Welsh Centre for Printing and Coating  |
| IST METZ GmbH | Yole Developpement | Western Michigan University |
| Jenoptik | Yutong Group | Wonkwang University |
| Johnson Matthey | Zebra Technologies | Wuhan University of Technology |
| Kateeva | ZEON Corporation  | Xi'an University of Technology |
| Kelenn Technology | Zinergy UK Ltd | Yamagata University |
| And more… |

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| **Topics including (but are not limited to):** |

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| **Materials & Technologies**• Substrate Material• Barrier Film• Encapsulation• Transparent Conductive Films• Conductive Inks• CNT Based• 2D Materials(Graphene)• Device Physics & Circuit Design• Electrical Measurement & Evaluation**Manufacturing Processes**• Additive manufacturing• Hybrid manufacturing• Scaling-up issues• Measurement and Reliability• Equipment (roll-to-roll, printing, coating etc)**Display & Lighting**• Displays• OLED• Electrophoretic• Electrochromic• Electroluminescent• Flexible LCD• Lighting• OLED• Printed LED**Sensor**• Biomedical• Touch• Temperature• Pressure• Image• Gas**Semiconductor**• Transistors• Memory**Energy**• Photovoltaics• Crystalline Silicon PV• Thin Film PV• Energy Storage• Single Use• Rechargeable• Energy Harvesting**End-User Industries**• Consumer Electronics• IoT• Automotive• Packaging & Logistics• Smart Building• Healthcare• Textiles & Fashion• Energy• Standards & Regulations**New Technologies & Application**  |

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| [**Paper Submission**](http://link.r2dmm.com/redirect.php?id=PDg3ODY0ZDhkZGNiYmY5YTMyYmRhN2UzZTBmNjEyZDg0QGxpbmsucjJkbW0uY29tPg%3D%3D&ref=aHR0cDovL3d3dy5pY2ZwZS5vcmcuY24vY2FsbC1mb3ItcGFwZXIv&e=1) |
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| **PROGRAM SCHEDULE** |

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| SEPT. 25, 2018 | SEPT. 26, 2018 | SEPT.  27, 2018 | SEPT.  28, 2018 |
|  **Workshop** Demo CompetitionRoad Show |  **Plenary Speech** （Industry & Academic） | Flexible Electronics 2018（Industry Session） | **Poster Session** |
| **Academic Sessions*** Materials & Technologies
* Manufacturing Processes
* Display & Lighting
* Sensor
* Semiconductor
* Energy
 | **Academic Sessions*** Materials & Technologies
* Manufacturing Processes
* Display & Lighting
* Sensor
* New Technologies & Application
 |
| Banquet |

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|  [Check More Details](http://demand-led.info/oem/tl.php?p=t4/rs/rs/s5/rt/rt//http%3A%2F%2Fwww.icfpe.org.cn%2Fabout-icpfe) |
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| **IMPORTANT DATES** |

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| Deadline for submission of one-page abstract | JUN 30, 2018 |
| Notification of acceptance of one-page abstract | JUL 15, 2018 |
| Early-bird registration | JUL 30, 2018 |
| Master Class - Workshop: Demo Competition Road Show | SEP 25, 2018 |
| ICFPE 2018 Conference & Exhibition | SEP 26 - 28, 2018 |

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| [Join Us](http://demand-led.info/oem/tl.php?p=t4/rs/rs/s5/rt/rt//http%3A%2F%2Fwww.icfpe.org.cn%2Fregister%2F) |

 http://www.icfpe.org.cn/wp-content/uploads/2017/12/footer-01-1.png |

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| We are looking forward to hearing from you soon! With best wishes! |

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